



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C020BB8NNNC
- Description : CAP, 2pF, 50V, ±0.1pF, C0G, 0603

A. Samsung Part Number

			<u>CL</u> ①	<u>10</u> ②	<u>C</u> 3	<u>020</u> ④	<u>B</u> (5)	<u>B</u> 6	<mark>8</mark> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>C</u> ①	
1	Series	Samsung M	/lulti-la	yer Ce	erami	c Capa	acito	r						
2	Size	0603 (ii	nch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Ni	
4	Capacitance	2 pf	F					Term	ninat	tion			Cu	
5	Capacitance	±0.1 p	F					Plati	ng			;	Sn 100%	(Pb Free)
	tolerance						9	Prod	luct				Normal	
6	Rated Voltage	50 V	,				10	Spec	cial				Reserved for	or future use
\bigcirc	Thickness	0.8 ±	0.1	mm			1	Pack	agir	ng			Cardboard	Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1₩±10% 0.5~5Vrms						
Q	440 min							
Insulation	10,000Mohm or 500Mohm . <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characterisitcs	(From -55 $^\circ\!\!\mathbb{C}$ to 125 $^\circ\!\!\mathbb{C}$, Capacitance change shoud be within ±30PPM/ $^\circ\!\!\mathbb{C}$)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within ±2.5% or ±0.25pF whichever is larger							
Tan δ, IR : initial spec.								

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 106.67 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 220 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.